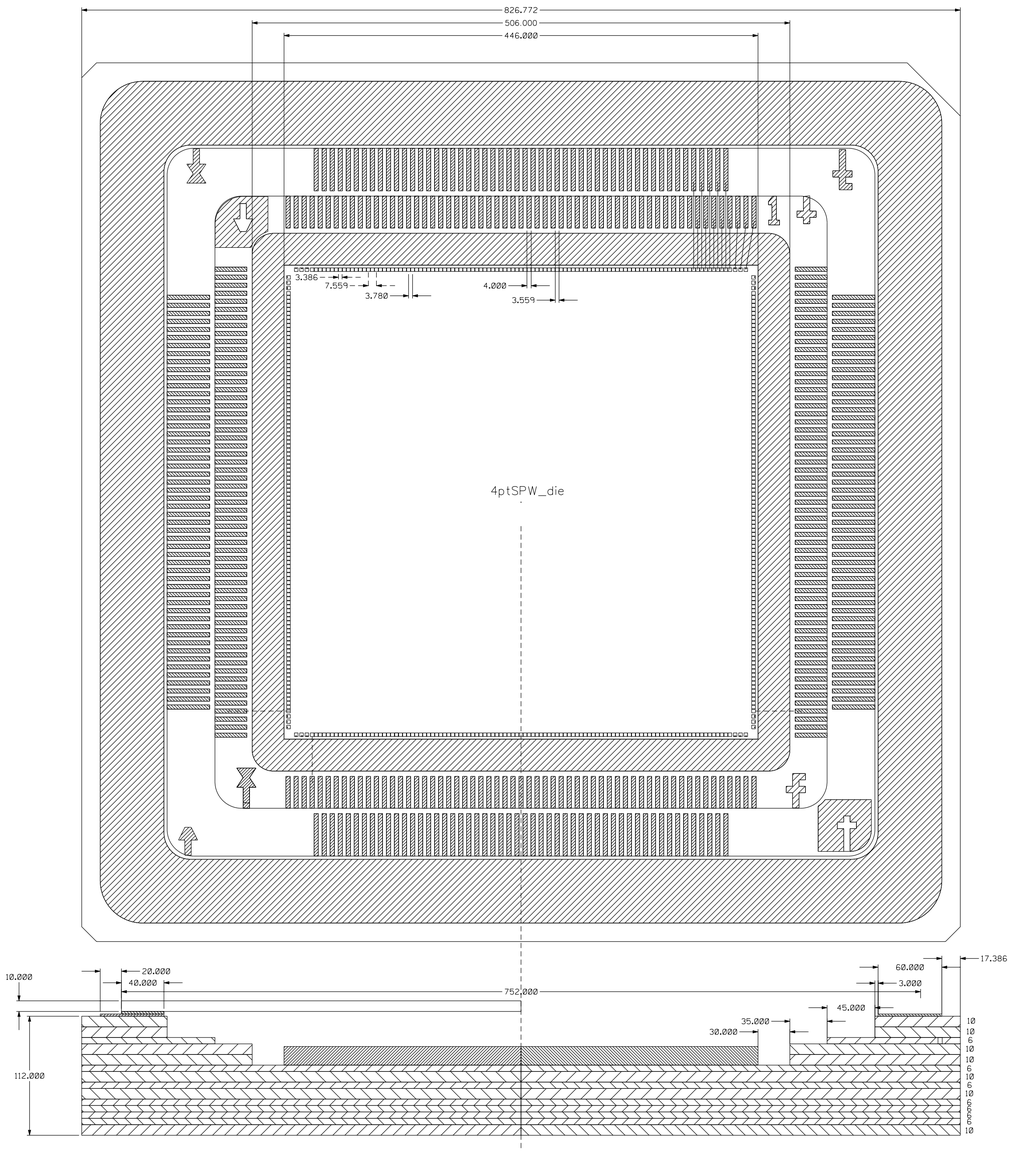
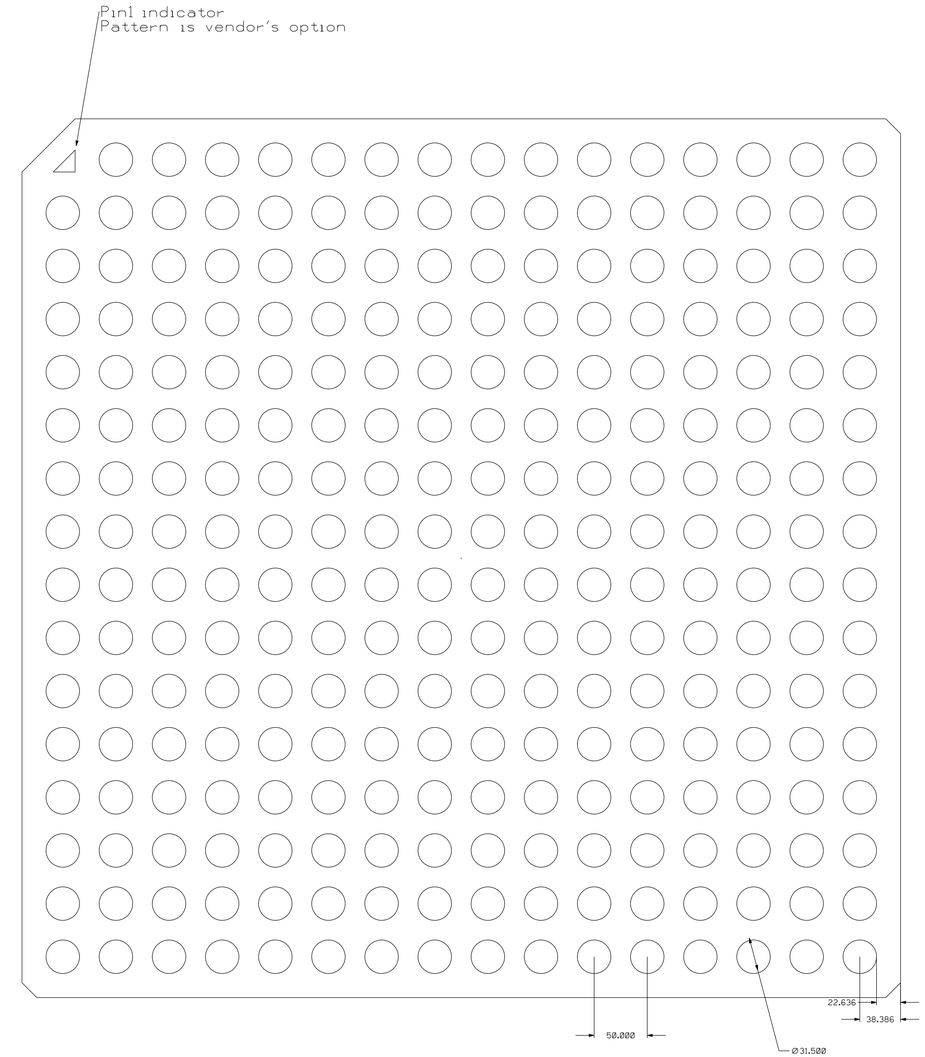
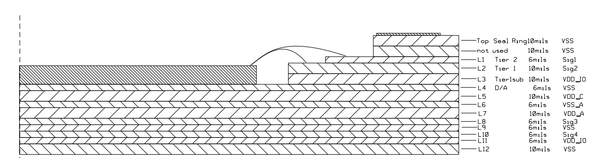






Stack-Up

NOTES:

1. PACKAGE MATERIAL: OPAQUE 90% MINIMUM ALUMINA CERAMIC.
2. ALL EXPOSED METAL AREAS MUST BE GOLD PLATED 100 TO 225 MICROINCHES THICK OVER ELECTROPLATED NICKEL UNDERCOATING 100 TO 350 MICROINCHES THICK PER MIL-PRF-38535.
3. THE SEAL RING MUST BE ELECTRICALLY CONNECTED TO VSS.
4. SEE UTMC SPEC. 40-7150-XX FOR FURTHER REQUIREMENTS.
5. PIN 1 ID MUST BE GOLD PLATED. NO ALPHANUMERIC FIGURES ALLOWED. MAY BE CONNECTED TO VSS FOR PLATING OPTIONAL.
6. BONDFINGER NUMBERS, LETTERS, AND I.D. ARE FOR REFERENCE ONLY.

DESIGN NOTES:

1. DRAWING UNITS ARE IN MILS
2. PACKAGE OUTLINE IS 21X21MM
3. DIE SIZE IS 446 MILS SQUARE
4. DIE BOND PAD PITCH IS 3.78 UM MIN
5. STANDARD ROUTING TRACE WIDTH IS ~4 MILS
6. VIA SIZES ARE 4 MILS AND 8 MILS
7. LGA PAD/OPENING SIZE IS 31.5 MILS
8. LAYOUT WILL REQUIRE LENGTH MATCHING AND CONTROLLED IMPEDANCE TRACES.
9. ROUTING AND STACK-UP PLANS WILL BE PROVIDED.
10. CONNECT FIDUCIALS TO VSS.
11. TYPICAL BONDFINGERS ARE 4 MILS WIDE, 3.56 MILS GAP.

DRAWING UNITS ARE IN MILS.

UNLESS OTHERWISE SPECIFIED: ALL DIMENSIONS ARE IN INCHES.

TOLERANCES:
ANGLES ± 3°
2 PLACE DEC. ±
3 PLACE DEC. ±
4 PLACE DEC. ±
±1% NLT ±0.005

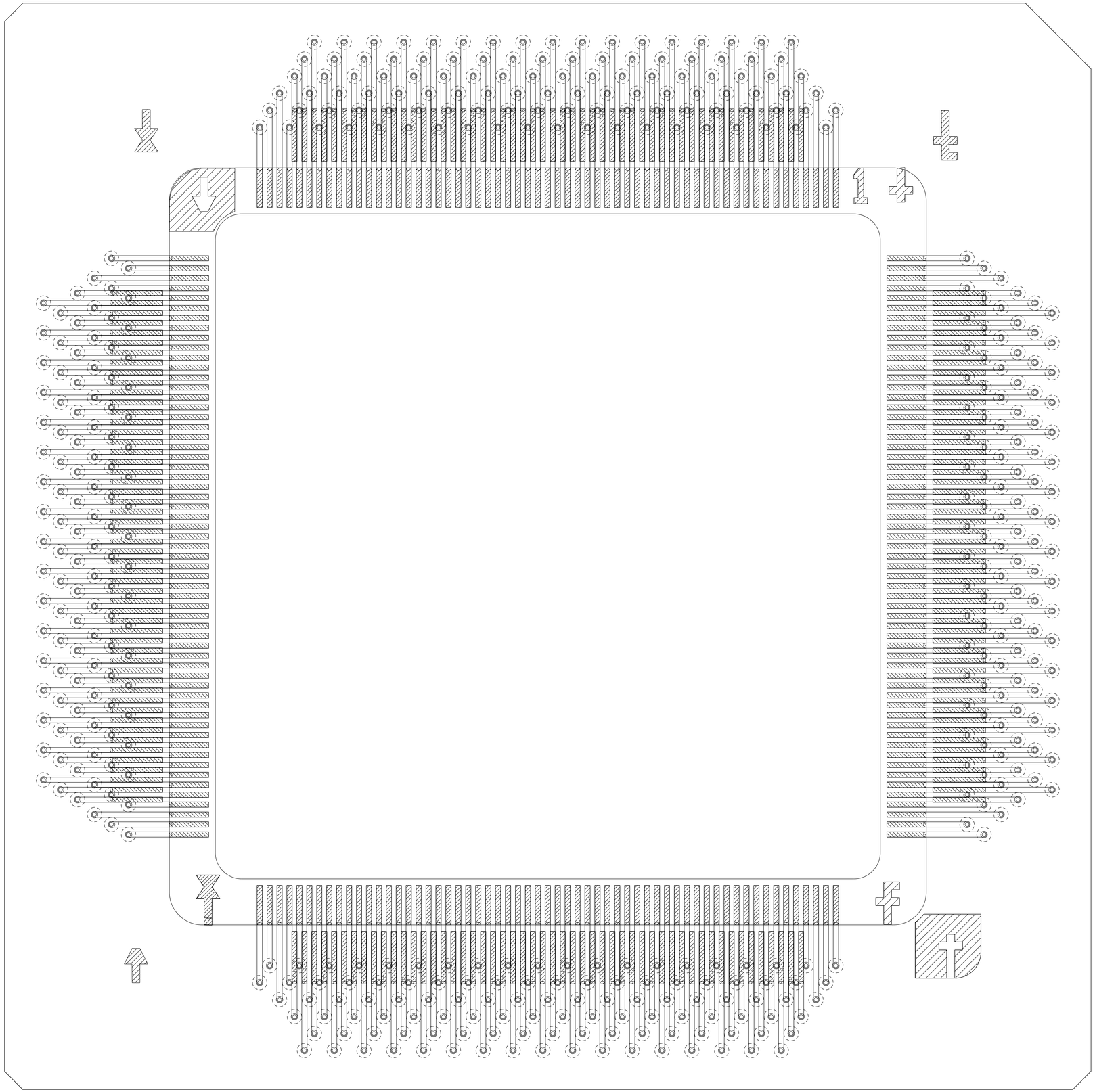
AEROFLEX

DRAWING DATE 26 FEB 2008

TITLE
255 LGA PACKAGE
0.506 SQ. CAVITY 21x21mm BODY
DETAIL DRAWING

REV PRELIM | DWG.#/DOC. CTRL.# 40-72018-YY

SCALE CAD | SIZE D | SHEET 1 OF 1



L1-Tier2
L2-Tier1